



IT-8615G

IT-8615G- Next Generation High DK Halogen free product for

- 4 G LTE Base Stations
- 5 G Base Stations & mm wave applications
- Antenna applications

Features

- Thermoset system with 200 °C Tg
- Very low loss ~0.0035 at 10 GHz.
- Halogen Free
- Excellent dimensional stability
- Very stable DK/Df with Temperature
- Ability to use very low profile Copper for reduced insertion loss.
- Highly suitable for Hybrids
- Ability to make high layer count boards
- Full prepreg offering

Data sheet - IT-8615G

Property		Units	IT-8615G
		Units	DK-6.15
THERMAL	Thickness		0.504(20 mils)
	Glass Transition Temp (Tg)	DMA	215
		DSC	203
		TMA	201
	Time to Delam (T300)	With Cu	> 60
	Solder Float		> 60
	Solder Dip (PCT@1 hour and 121°C)		> 60
	Thermal Decomposition Temp (5wt%)		434
	CTE: RT-150°C	X-axis	15.1
	CTE: RT-150°C	Y-axis	14.0
	CTE:α1	Z - axis	49
	CTE:α2	Z - axis	220
CTE	Z - axis	1.90	
ELECTRICAL	Thickness		0.504(20 mils)
	Dielectric Constant (Dk)	@2GHz	6.15
		@3GHz	6.15
		@5GHz	6.15
		@10GHz	6.15
	Dielectric Factor (Df)	@2GHz	0.0035
		@3GHz	0.0036
		@5GHz	0.0037
@10GHz		0.0037	
PHYSICAL	Water Absorption		0.18
	Peel Strength	1 oz (RTF)	>4.0
	Flammability	-	V0
	Thermal Conductivity		0.62
	Elastic modulus	X-axis	18.10
Y-axis		17.60	